

## MiniSKiiP<sup>®</sup> 3 Dual

## Half-Bridge

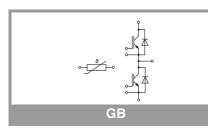
### SKiiP 38GB07E3V1

### Features\*

- 650V Trench IGBTs
- · Robust and soft diodes in CAL
- technologyHighly reliable spring contacts for electrical connections
- UL recognised: File no. E63532
- NTC T-Sensor

### Remarks

- Max. case temperature limited to T<sub>C</sub>= 125°C
- Product reliability results valid for  $T_j \le 150^{\circ}C$  (recommended  $T_{j,op} = -40...+150^{\circ}C$ )



Absolute	Maximum Rati	ngs		
Symbol	Conditions		Values	Unit
Inverter -	IGBT			•
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		650	V
lc	T <sub>i</sub> = 175 °C	T <sub>s</sub> = 25 °C	287	А
	1j=1/5 0	T <sub>s</sub> = 70 °C	228	А
I <sub>Cnom</sub>			300	А
I <sub>CRM</sub>			900	A
V <sub>GES</sub>			-20 20	V
t <sub>psc</sub>	$V_{CC} = 360 V$ $V_{GE} \le 15 V$ $V_{CES} \le 650 V$	T <sub>j</sub> = 150 °C	6	μs
Tj			-40 175	°C
Inverse -	Diode			
I <sub>F</sub>	T <sub>i</sub> = 175 °C	T <sub>s</sub> = 25 °C	310	А
	$1_j = 175 \text{ C}$	T <sub>s</sub> = 70 °C	241	A
I <sub>FRM</sub>			600	A
I <sub>FSM</sub>	10 ms, sin 180°	, T <sub>j</sub> = 150 °C	1980	A
Tj			-40 175	°C
Module	·			
I <sub>t(RMS)</sub>	T <sub>terminal</sub> = 80 °C, per spring	T <sub>terminal</sub> = 80°C, 20A	280	A
T <sub>stg</sub>	module without	TIM	-40 125	°C
V <sub>isol</sub>	AC sinus 50 Hz	t = 1 min	2500	V

### 

	chipievei	1					
V <sub>CE0</sub>	chiplevel	T <sub>j</sub> = 25 °C		0.90	1.00	V	
		T <sub>j</sub> = 150 °C		0.82	0.90	V	
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25 °C		1.83	3.0	mΩ	
	chiplevel	T <sub>j</sub> = 150 °C		2.9	4.0	mΩ	
V <sub>GE(th)</sub>	$V_{GE} = V_{CE}, I_C = 4.8$	mA	5.1	5.8	6.4	V	
I <sub>CES</sub>	V <sub>GE</sub> = 0 V	T <sub>j</sub> = 25 °C			3.0	mA	
	V <sub>CE</sub> = 650 V			-		mA	
Cies	N 05.14	f = 1 MHz		18.48		nF	
C <sub>oes</sub>	V <sub>CE</sub> = 25 V V <sub>GE</sub> = 0 V	f = 1 MHz		1.16		nF	
C <sub>res</sub>	VGE - 0 V	f = 1 MHz		0.55			
$Q_{G}$	- 8 V+ 15 V			2400		nC	
R <sub>Gint</sub>	T <sub>j</sub> = 25 °C			1.0		Ω	
t <sub>d(on)</sub>	V <sub>CC</sub> = 300 V	T <sub>j</sub> = 150 °C		86		ns	
t <sub>r</sub>	$I_{C} = 300 \text{ A}$ $R_{G \text{ on}} = 3 \Omega$	T <sub>j</sub> = 150 °C		73		ns	
Eon	$R_{G \text{ off}} = 3 \Omega$	T <sub>j</sub> = 150 °C		5.5		mJ	
t <sub>d(off)</sub>	di/dt <sub>on</sub> = 4985 A/µs	T <sub>j</sub> = 150 °C		530		ns	
t <sub>f</sub>	di/dt <sub>off</sub> = 5375 A/ $\mu$ s	T <sub>j</sub> = 150 °C		64		ns	
E <sub>off</sub>	dv/dt = 4000 V/μs V <sub>GE</sub> = +15/-8 V L <sub>s</sub> = 25 nH	T <sub>j</sub> = 150 °C		10.6		mJ	
R <sub>th(j-s)</sub>	per IGBT, $\lambda_{paste}=0.8$	3 W/(K*m)		0.25		K/W	

Unit

V

٧

max.

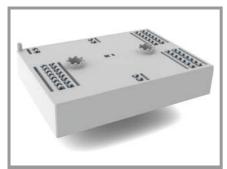
1.90

2.10

typ.

1.45

1.70



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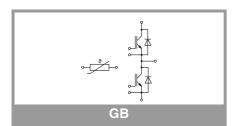
### Features\*

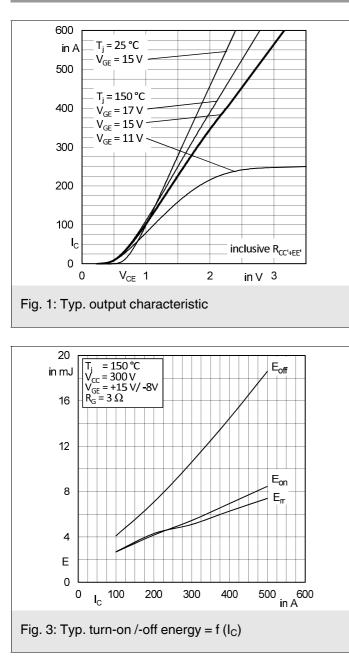
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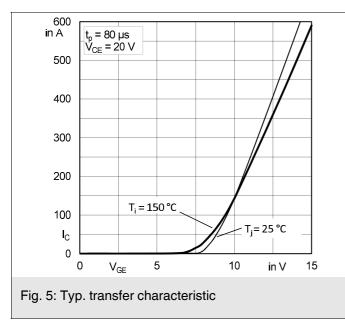
### Remarks

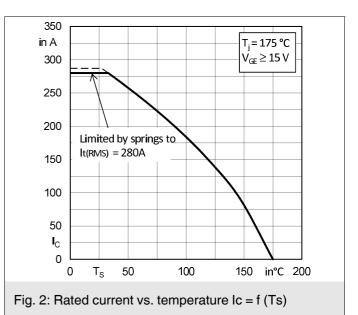
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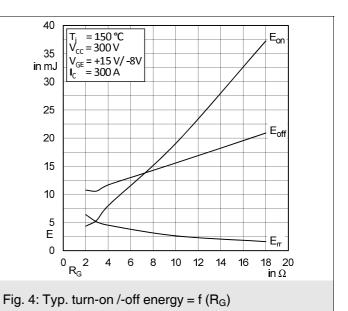
Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Unit
Inverse -	Diode					
$V_F = V_{EC}$	I <sub>F</sub> = 300 A	T <sub>j</sub> = 25 °C		1.40	1.76	V
	V <sub>GE</sub> = 0 V chiplevel	T <sub>j</sub> = 150 °C		1.39	1.77	V
V <sub>F0</sub>	abialoval	T <sub>j</sub> = 25 °C		1.04	1.24	V
	- chiplevel	T <sub>j</sub> = 150 °C		0.85	0.99	V
r <sub>F</sub>	abialoval	T <sub>j</sub> = 25 °C		1.19	1.76	mΩ
	chiplevel	T <sub>j</sub> = 150 °C		1.79	2.6	mΩ
I <sub>RRM</sub>	I <sub>F</sub> = 300 A	T <sub>j</sub> = 150 °C		247		Α
Q <sub>rr</sub>	$di/dt_{off} = 4990 \text{ A}/\mu \text{s}$	T <sub>j</sub> = 150 °C		22.6		μC
E <sub>rr</sub>		T <sub>j</sub> = 150 °C		5.1		mJ
R <sub>th(j-s)</sub>	per Diode, $\lambda_{\text{paste}}=0$ .		K/W			
Module	•					
L <sub>CE</sub>				15		nH
Ms	to heat sink		2		2.5	Nm
w				76		g
Temperat	ure Sensor					•
R <sub>100</sub>	T <sub>c</sub> =100°C (R <sub>25</sub> =5 k		Ω			
B <sub>25/85</sub>	R(T)=R25*exp[B25/85		K			











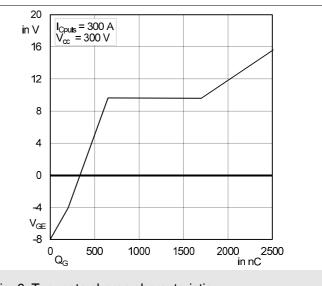
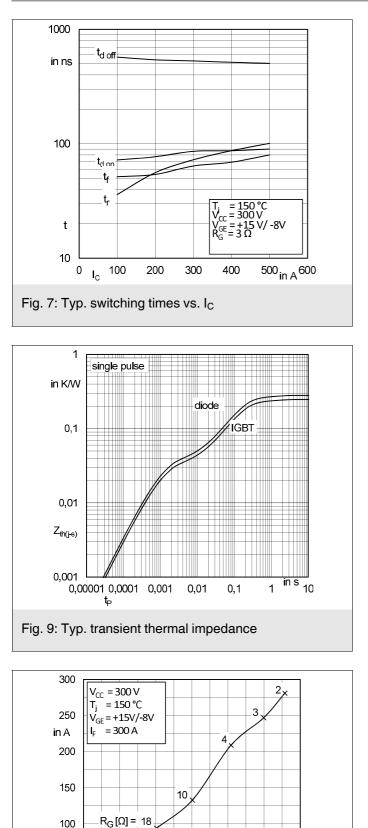


Fig. 6: Typ. gate charge characteristic



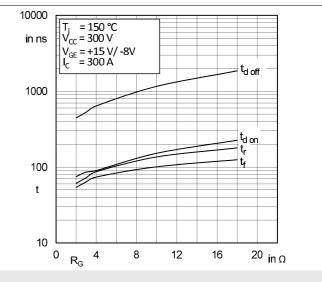
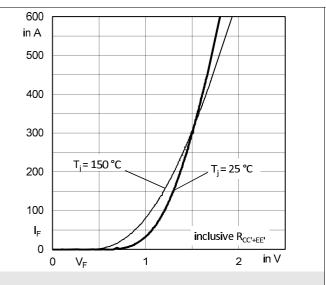
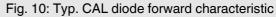
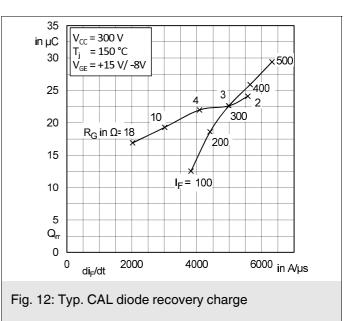


Fig. 8: Typ. switching times vs. gate resistor R<sub>G</sub>







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100

50

 $\mathbf{I}_{\mathsf{RR}}$ 

0

0

di<sub>F</sub>/dt

1000

2000

3000

Fig. 11: Typ. CAL diode peak reverse recovery current

4000

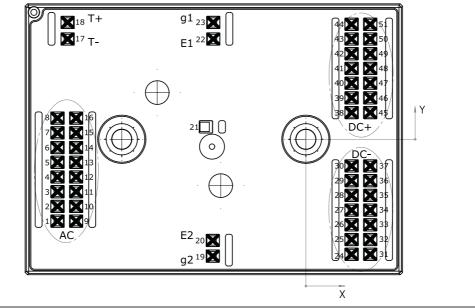
5000

in A/µs

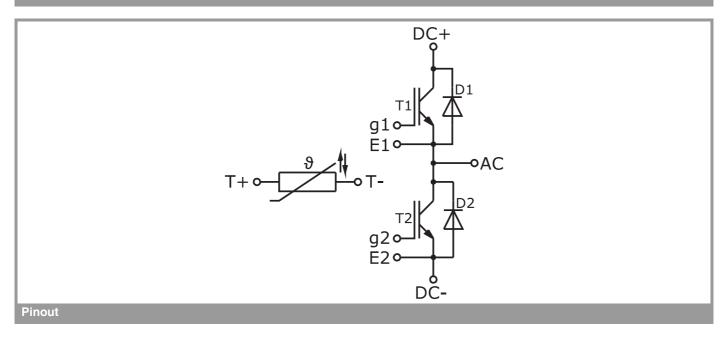
6000

	Pin out										
Pin	X	Y	Function	Pin	X	Y	Function	Pin	X	Y	Function
1	-53,98	-17,80	AC	18	-51,78	25,40	T+	35	13,98		DC-
2	-53,98	-14,60	AC	19	-20,23	-25,40	g2	36	13,98	-9,00	DC-
3	-53,98	-11,40	AC	20	-20,23	-22,00	E2	37	13,98	-5,80	DC-
4	-53,98	-8,20	AC	21	-21,73	2,70		38	9,93	5,80	DC+
5	-53,98		AC	22	-20,13		E1	39	9,93	9,00	DC+
6	-53,98	-1,80	AC	23	-20,13	25,40	g1	40	9,93	12,20	DC+
7	-53,98	1,40	AC	24	9,93	-25,00	DC-	41	9,93	15,40	DC+
8	-53,98	4,60	AC	25	9,93	-21,80	DC-	42	9,93	18,60	DC+
9	-49,93	-17,80	AC	26	9,93	-18,60	DC-	43	9,93	21,80	DC+
10	-49,93	-14,60	AC	27	9,93	-15,40	DC-	44	9,93	25,00	DC+
11	-49,93	-11,40	AC	28	9,93	-12,20	DC-	45	13,98	5,80	DC+
12	-49,93	-8,20	AC	29	9,93	-9,00	DC-	46	13,98	9,00	DC+
13	-49,93	-5,00	AC	30	9,93	-5,80	DC-	47	13,98	12,20	DC+
14	-49,93	-1,80	AC	31	13,98	-25,00	DC-	48	13,98	15,40	DC+
15	-49,93	1,40	AC	32	13,98	-21,80	DC-	49	13,98	18,60	DC+
16	-49,93	4,60	AC	33	13,98	-18,60	DC-	50	13,98	21,80	DC+
17	-51,78	21,80	Т-	34	13,98	-15,40	DC-	51	13,98	25,00	DC+

all values in [mm]



**Pinout and Dimensions** 



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

### **\*IMPORTANT INFORMATION AND WARNINGS**

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